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Part Number: [0737821100](#)
Status: **Active**
Overview: [hdm](#)
Description: 2.00mm (.079") Pitch HDM® Board-to-Board Stacking Header, High Rise Vertical, SMC, Closed End Option, 144 Circuits

Documents:

[3D Model](#) [Product Specification PS-73780-999 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification

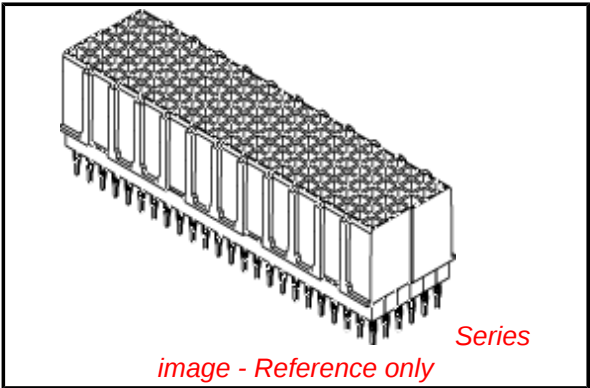
CSA LR19980
UL E29179

General

Product Family Backplane Connectors
Series [73782](#)
Application Backplane, Mezzanine
Component Type PCB Header
Overview [hdm](#)
Product Name HDM®
Style N/A

Physical

Circuits (Loaded) 144
Circuits (maximum) 144
Color - Resin Black
Durability (mating cycles max) 200
First Mate / Last Break No
Flammability 94V-0
Guide to Mating Part No
Keying to Mating Part None
Material - Metal Phosphor Bronze
Material - Plating Mating Gold
Material - Plating Termination Tin-Lead
Material - Resin High Temperature Thermoplastic
Number of Columns 24
Number of Pairs Open Pin Field
Number of Rows 6
Orientation Vertical
PC Tail Length (in) 0.079 In
PC Tail Length (mm) 2.00 mm
PCB Retention None
PCB Thickness Recommended (in) 0.055 In
PCB Thickness Recommended (mm) 1.40 mm
Packaging Type Tube
Pitch - Mating Interface (in) 0.079 In
Pitch - Mating Interface (mm) 2.00 mm
Plating min: Mating (µin) 30
Plating min: Mating (µm) 0.75
Plating min: Termination (µin) 100
Plating min: Termination (µm) 2.5
Polarized to PCB No
Stackable Yes
Surface Mount Compatible (SMC) Yes
Temperature Range - Operating -55°C to +105°C



EU RoHS

**ELV and RoHS
Compliant**
**REACH SVHC
Contains SVHC: No**
**Halogen-Free
Status**

China RoHS



**Need more information on product
environmental compliance?**

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of
Compliance, [click here](#)

Please visit the [Contact Us](#) section for any
non-product compliance questions.

Search Parts in this Series

[73782Series](#)

Mates With

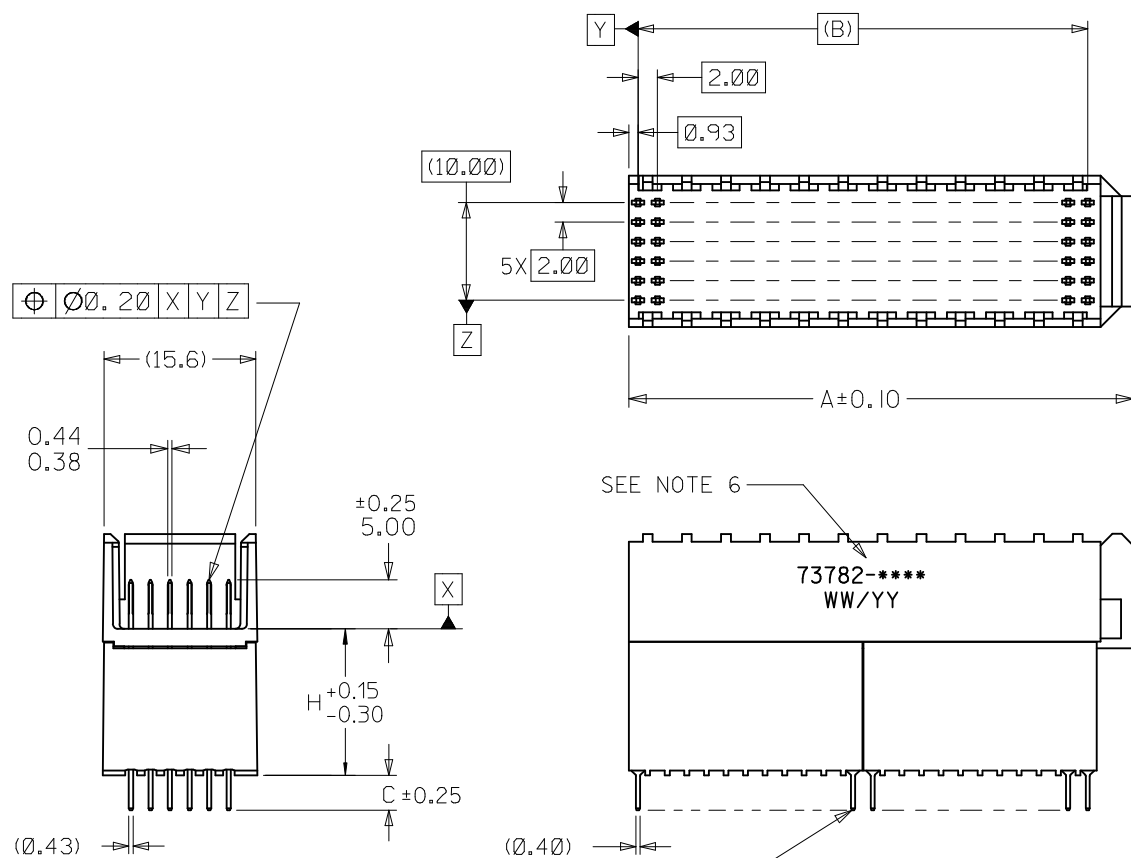
[73632](#) HDM PLUS® Board-to-Board
Daughtercard Receptacle. [73780](#) HDM®
Board-to-Board Daughtercard Receptacle

Termination Interface: Style	Through Hole
Electrical	
Current - Maximum per Contact	1A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	72
Voltage - Maximum	100V AC
Solder Process Data	
Duration at Max. Process Temperature (seconds)	5
Lead-free Process Capability	Wave Capable (TH only)
Max. Cycles at Max. Process Temperature	1
Process Temperature max. C	260
Material Info	
Reference - Drawing Numbers	
Packaging Specification	PK-70873-0870
Product Specification	PS-73780-999
Sales Drawing	SD-73782-001

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NOTES:

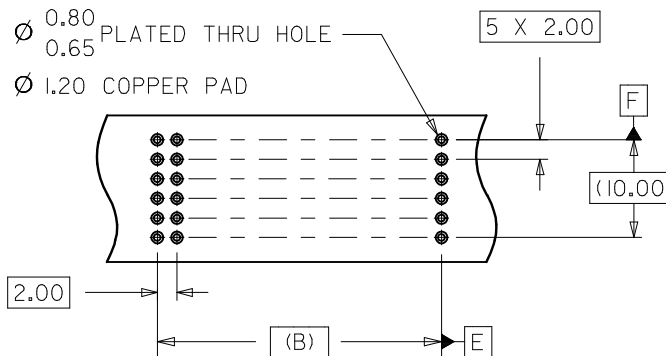
1. MATERIALS: HOUSING-LIQUID CRYSTAL POLYMER (LCP), GLASS-FILLED, UL94V-0, COLOR: BLACK.
TERMINAL-PHOSPHOR BRONZE
2. FINISH:
0.75 MICROMETERS MINIMUM SELECTIVE GOLD IN MATING AREA
2.50 MICROMETERS MINIMUM SELECTIVE TIN IN TAIL AREA
NICKEL UNDERPLATE OVERALL.
3. THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION PS-73780-999.
4. THIS PART CONFORMS TO MOLEX COSMETIC SPECIFICATION PS-45499-002 CLASS C.
5. PACKAGE PER PK-70873-0870, PK-70873-0871, OR PK-70873-0875.
6. PARTS MARKED WITH PART NUMBER AND DATE CODE APPROXIMATELY WHERE SHOWN.

⊕ Ø0.15 (M) E F

Ø 0.838 DRILL

Ø 0.80
0.65 PLATED THRU HOLE

Ø 1.20 COPPER PAD



BACKPLANE HOLE PATTERN

⊕ Ø0.15 (M) X Y Z

REVISE DIM H TOL EC NO: UCP2008-3186 DRWN:SDANNELLEY 2008/07/29 CHKD:MSIBARRA 2008/09/11 APPR:SMILLER 2008/09/16	QUALITY SYMBOLS ▽=0 ▽=0	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION				
				mm	INCH	DRAWN BY JB INGHAM	DATE 1997/04/25	TITLE SALES ASSEMBLY, HDM BACKPLANE STACKING MOD CLOSED END SOLDER					
			4 PLACES	± ---	± ---	CHECKED BY	DATE						
			3 PLACES	± ---	± ---	SREED	1997/04/25						
			2 PLACES	± 0.05	± ---	APPROVED BY	DATE						
			1 PLACE	± 0.10	± ---	CBIXLER	1997/04/25	MOLEX		MOLEX INCORPORATED			
			ANGULAR ±1/2°			MATERIAL NO.		DOCUMENT NO.		SHEET NO.			
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SEE TABLE		SD-73782-001		1 OF 2			
						SIZE B	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

MATERIAL NUMBER ASSIGNMENT

73782-* * 0 0

NUMBER	CIRCUIT SIZE	DIM "A"	DIM "B"	DIM "C"
0	72	27.6	22.00	2.0
1	144	51.6	46.00	2.0
2	72	27.6	22.00	2.5
3	144	51.6	46.00	2.5
4	72	27.6	22.00	3.0
5	144	51.6	46.00	3.0
6	72	27.6	22.00	3.5
7	144	51.6	46.00	3.5

NUMBER	DIM "H"
1	15.05
2	6.05
3	10.05

SEE SHEET 1 EC NO: UCP2008-3186 DRAWN: SPANIELLEY 2008/07/29 CHKD: MSIBARRA 2008/09/11 APPR: SMILLER 2008/09/16	DESCRIPTION REV	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	mm	INCH	DRAWN BY JB INGHAM	DATE 1997/04/25	TITLE SALES ASSEMBLY, HDM BACKPLANE STACKING MOD CLOSED END SOLDER				
			4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	CHECKED BY SREED	DATE 1997/04/25					
			2 PLACES ± 0.05 ± ---	1 PLACE ± 0.10 ± ---	APPROVED BY CBIXLER	DATE 1997/04/25	MOLEX INCORPORATED				
			ANGULAR ± 1/2°		MATERIAL NO. SEE TABLE						
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION											

MATERIAL NUMBER ASSIGNMENT

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6	72	27.6	22.00	3.5
7	144	51.6	46.00	3.5

NUMBER	DIM "H"
1	15.05
2	6.05
3	10.05

SEE SHEET 1 EC NO. UDT2000-1073 DRWN:JBINGHAM 0000508 CHK: REED 0000508 APPR:CBIXLER 0000508 F	DESCRIPTION MAJOR CRITICAL	QUALITY SYMBOLS		GENERAL TOLERANCES: (UNLESS SPECIFIED)		SCALE NO:NE	DESIGN UNITS ☒ mm ☐ INCH	DIMENSIONS: ☐ mm ☐ INCH ☒ mm ONLY		SHT	REV
						DRAWN BY & DATE JBINGHAM 97/04/25		THIRD ANGLE PROJECTION		REVISE ON CAD ONLY	
						CHECKED BY & DATE SREED 97/04/25		TITLE: SALES ASSEMBLY HDM BACKPLANE STACKING MODULE CLOSED END OPTION SOLDER TAIL			
						APPROVED BY & DATE CBIXLER 97/04/25		MOLEX INCORPORATED			
						CAD FILENAME S73782X2.DGN		MATERIAL NO. SEE CHART		DRAWING NO. SD-73782-001	SHEET NO. 2
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.					

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Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

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